

MENU**SEARCH****INDEX****JAPANESE****LEGAL
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1 / 1

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(71)
Applicant : **MATSUSHITA ELECTRIC IND
CO LTD**

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(54) MAGNETRON SPUTTERING DEVICE

(57)Abstract:

PURPOSE: To improve the utilizing efficiency of a target, film thickness distribution and film forming speed by mounting plural pieces of magnet pairs of a cathode part eccentrically from the center of the target toward the outside peripheral direction.

CONSTITUTION: The magnetron type cathode and substrate are provided in a vacuum chamber. The plural magnet pairs 23 are disposed at equal intervals to the cathode 21 on the same pitch circumference concentric with the central axis of the target 25. The magnet pairs 23 are magnet S poles (or N pole) having a sectorial, triangular or trapezoidal sectional shape and the N poles (or S poles) disposed at equal intervals on the outside periphery thereof. The magnets are rotated around the target 25.

